



DCR3910Y22

Replaces DS5886-1.2

DS5886-2 July 2023 (LN42666)

Phase Control Thyristor

FEATURES

- Double Side Cooling
- High Surge Capability

APPLICATIONS

- High Power Drives
- High Voltage Power Supplies
- Static Switches

VOLTAGE RATINGS

Part and Ordering Number	Repetitive Peak Voltages Vdrm and Vrrm (V)	Conditions
DCR3910Y22 DCR3910Y20 DCR3910Y18	2200 2000 1800	$T_{vj} = -40^{\circ}C \text{ to } 125^{\circ}C,$ IDRM = IRRM = 200mA, $VDRM, VRRM t_{P} = 10ms$ VDSM & VRSM = VDRM & VRRM + 100V respectively

Lower voltage grades available.

ORDERING INFORMATION

When ordering, select the required part number shown in the Voltage Ratings selection table.

For example:

DCR3910Y22

Note: Please use the complete part number when ordering and quote this number in any future correspondence relating to your order.

KEY PARAMETERS				
Vdrm	2200V			
Τ(Αν)	3890A			
тѕм	54000A			
dV/dt*	1500V/µs			
dl/dt	300A/µs			

* Higher dV/dt selections are available on request

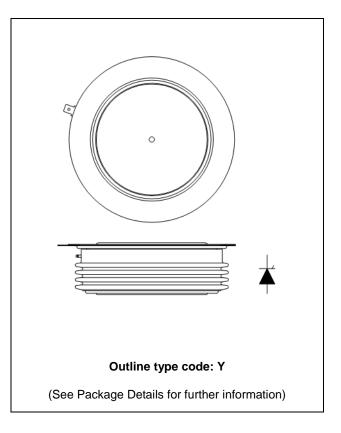


Fig. 1 Package outline

CURRENT RATINGS

T_{case} = 60°C unless stated otherwise

Symbol	Parameter	Test Conditions	Max.	Units
Double Si	de Cooled			
Ιτ(Αν)	Mean on-state current	Half wave resistive load	3890	А
It(rms)	RMS value	-	6110	А
lτ	Continuous (direct) on-state current	-	5390	А

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SURGE RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
Ітѕм	Surge (non-repetitive) on-state current	10ms half sine, Tcase = 125°C	54.0	kA
l²t	I ² t for fusing	VR = 0	14.6	MA ² s

THERMAL AND MECHANICAL RATINGS

Symbol	Parameter	Test Conditior	Min.	Max.	Units	
		Double side cooled	DC	-	8.4	°C/kW
Rth(j-c)	Thermal resistance - junction to case		Anode DC	-	13.4	°C/kW
		Single side cooled	Cathode DC	-	23.1	°C/kW
		Clamping force 54kN	Double side	-	2.0	°C/kW
Ktn(c-n)	Rth(c-h) Thermal resistance - case to heatsink	(with mounting compound)	Single side	-	4.0	°C/kW
Tvj	Virtual junction temperature	Blocking Vdrm / Vrrm	·	-	125	°C
Tstg	Storage temperature range			-55	125	°C
Fm	Clamping force			48	59	kN

DYNAMIC CHARACTERISTICS

Symbol	Parameter	Test Condition	IS	Min.	Max.	Units
Irrm/Idrm	Peak reverse and off-state current	At VRRM/VDRM, Tcase = 125°C	At Vrrm/Vdrm, Tcase = 125°C		200	mA
Vтм	Instantaneous forward voltage	At 4000A peak, Tj = 125°C		1.15	1.30	V
dV/dt	Max. linear rate of rise of off-state voltage	То 67% V _{DRM} , Тј = 125°С, ga	ate open	-	1500	V/µs
dl/dt	Rate of rise of on-state current	From 67% VDRM to 2x $I_{T(AV)}$ Gate source 30V, 10 Ω	Repetitive 50Hz	-	150	A/µs
di/dt		tr < 0.5µs, Tj = 125°C	Non-repetitive	-	300	A/µs
	Threshold voltage - Low level 500A to 2300A at Tcase = 125°C		-	0.78	V	
V τ(το)	Threshold voltage - High level	2300A to 7000A at T _{case} = 125°C		-	0.92	V
_	On-state slope resistance - Low level	n-state slope resistance - Low level 500A to 2300A at T _{case} = 125°C		-	0.16	mΩ
ľτ	On-state slope resistance - High level	2300A to 7000A at Tcase = 125°C		-	0.10	mΩ
tgd	Delay time	$V_{D} = 67\% V_{DRM}, \text{ gate source } 30V, 10\Omega$ tr = 0.5µs, Tj = 25°C		-	3	μs
tq	Turn-off time	Tj = 125°C, V _R = 200V, dl/dt = 1A/µs, dV _{DR} /dt = 20V/µs linear		-	600	μs
Qs	Stored charge $I_T = 2000A, T_j = 125^{\circ}C, dI/dt = 1A/\mu s$		390	1920	μC	
Irr	Reverse recovery current	VR(peak) ~ 1300V, Vrм ~ 900V		17	36	А
IL.	Latching current	Tj = 25°C, VD = 5V		-	3	А
Ін	Holding current	Тј = 25°С, Rg-к = ∞, Iтм = 50	0A, I⊤ = 5A	-	300	mA

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GATE TRIGGER CHARACTERISTICS AND RATINGS

Symbol	Parameter	Test Conditions	Max.	Units
Vgt	Gate trigger voltage	Vdrm = 5V, Tcase = 25°C	1.5	V
Vgd	Gate non-trigger voltage	At 50% Vdrm, Tcase = 125°C	0.4	V
Іст	Gate trigger current	Vdrm = 5V, Tcase = 25°C	250	mA
Igd	Gate non-trigger current	At 50% Vdrm, Tcase = 125°C	10	mA

CURVES

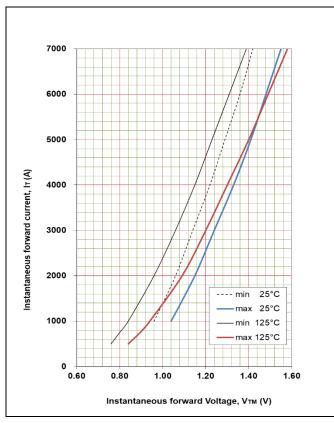


Fig. 2 Maximum & minimum on state characteristics

VTM EQUATION

$$V_{TM} = A + B.ln(I_T) + C.I_T + D.\sqrt{I_T}$$

Where A = 0.404689 B = 0.051381 C = 0.000056 D = 0.003938 These values are valid for $T_j = 125^{\circ}C$ for I_T 500A to 7000A

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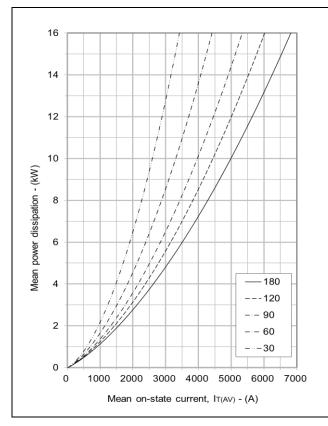


Fig. 3 On-state power dissipation - sine wave

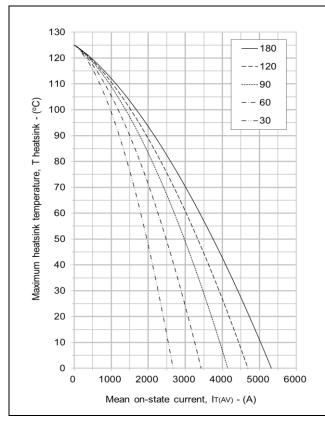


Fig. 5 Maximum permissible heatsink temperature, double side cooled - sine wave

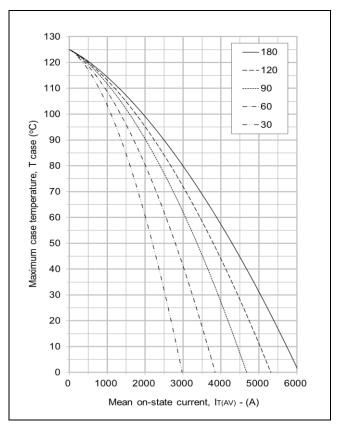


Fig. 4 Maximum permissible case temperature, double side cooled - sine wave

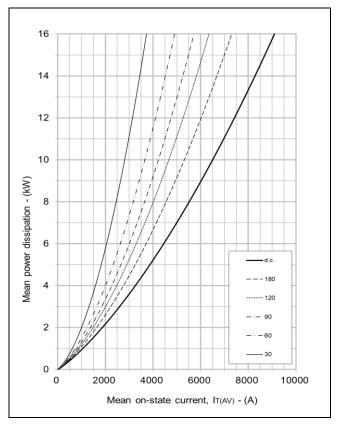


Fig. 6 On-state power dissipation - rectangular wave

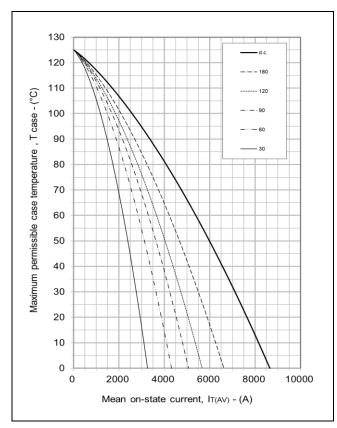
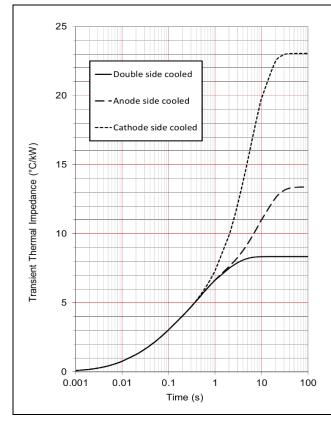


Fig. 7 Maximum permissible case temperature, double side cooled - rectangular wave



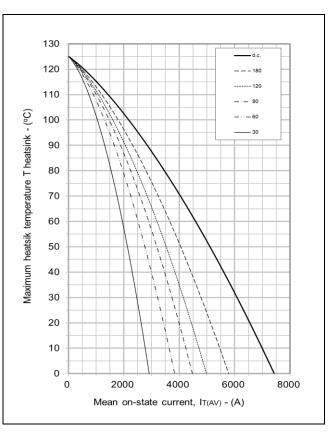


Fig. 8 Maximum permissible heatsink temperature, double side cooled - rectangular wave

		1	2	3	4
Double side	Ri(°C/kW)	0.612	1.772	3.105	2.861
cooled	Ti(s)	0.010	0.056	0.333	1.632
Anode side cooled	Ri(°C/kW)	0.701	1.939	3.610	7.138
	Ti(s)	0.011	0.066	0.420	9.061
Cathode side	Ri(°C/kW)	0.673	2.017	1.731	18.639
cooled	Ti(s)	0.011	0.066	0.304	5.727

$$Z_{th} = \sum_{i=1}^{i=4} R_i \cdot \left(1 - \exp\left(-\frac{T}{T_i}\right)\right)$$

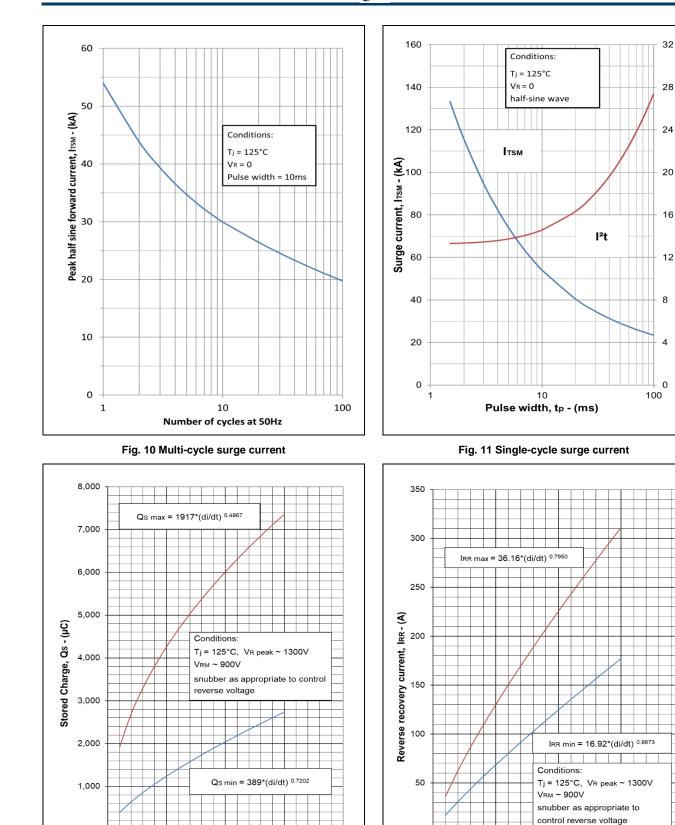
 $\Delta R_{th(j-c)}$ Conduction

Tables show the increments of thermal resistance $R_{\text{th}(j\text{-c})}$ when the device operates at conduction angles other than d.c.

D	Double side cooling		Anode Side Cooling			Cathode Sided Cooling				
	∆Zth	(Z)			ΔZ_t	_h (Z)			ΔZt	h (Z)
θ°	sine.	rect.		θ°	sine.	rect.		θ°	sine.	rect.
180	0.94	0.65		180	0.94	0.64		180	0.94	0.64
120	1.09	0.92		120	1.08	0.91	Ŀ	120	1.08	0.91
90	1.24	1.07		90	1.23	1.06		90	1.24	1.06
60	1.38	1.23		60	1.37	1.22		60	1.37	1.22
30	1.49	1.40		30	1.47	1.38		30	1.48	1.39
15	1.54	1.49		15	1.52	1.47		15	1.53	1.48



I²t value - (MA²s)



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0 -

0

5

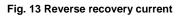
10

Rate of decay of on-state current, di/dt - (A/µs)

Fig. 12 Stored charge

15

20



5

10

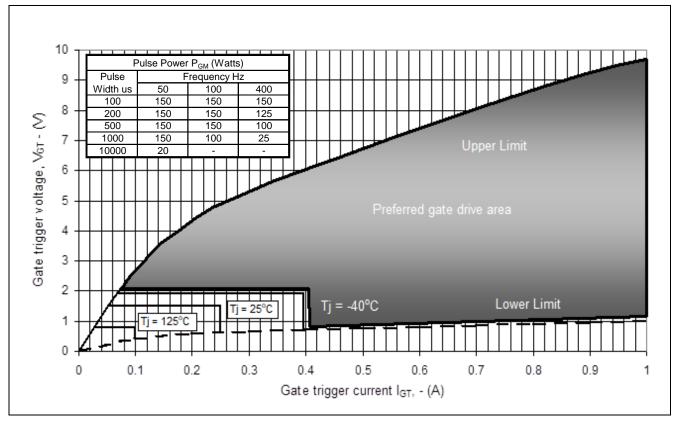
Rate of decay of on-state current, di/dt - (A/µs)

15

0 -

0

20



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Fig. 14 Gate characteristics

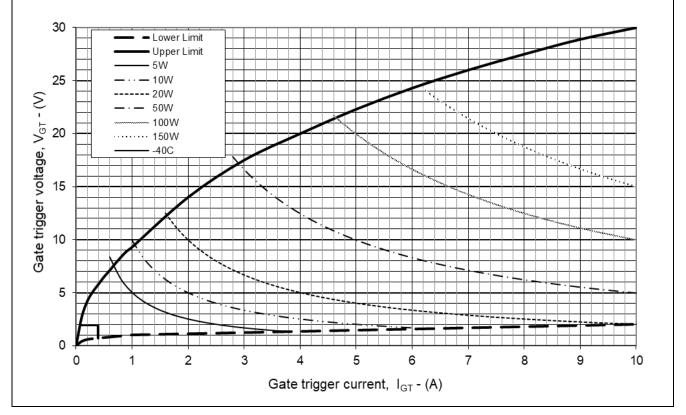


Fig. 15 Gate characteristics

Minimum

(mm)

35.4

35.1

34.9

34.7

34.5

34.4

34.3

PACKAGE DETAILS

For further package information, please contact Customer services.

All dimensions in mm, unless stated otherwise.

DO NOT SCALE

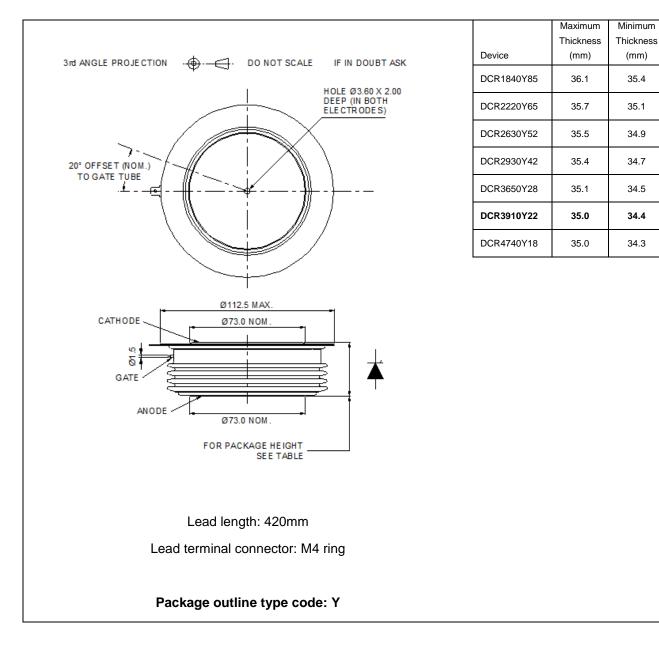


Fig. 16 Package outline

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